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Solder paste — Part 1: Kinds and quality classification

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Foreword

This translation has been made based on the original Japanese Industrial Standard established by the Minister of Economy, Trade and Industry through deliberations at the Japanese Industrial Standards Committee according to the proposal for establishment of Japanese Industrial Standard submitted by The Japan Welding Engineering Society (JWES) with the draft being attached, based on the provision of Article 12 Clause 1 of the Industrial Standardization Law.

Consequently **JIS Z 3284**:1994 has been withdrawn and partially replaced with this Standard.

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Attention is drawn to the possibility that some parts of this Standard may conflict with patent rights, applications for a patent after opening to the public or utility model rights. The relevant Minister and the Japanese Industrial Standards Committee are not responsible for identifying any of such patent rights, applications for a patent after opening to the public or utility model rights.

JIS Z 3284 series consists of the following 4 parts under the general title "*Solder paste —*" :

Part 1 : Kinds and quality classification

Part 2 : Test methods for solder particle shape, surface condition judgment, and particle size distribution

Part 3 : Test methods for printability, viscosity, slump and tackiness

Part 4 : Test methods for wettability, solderball and spread

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Solder paste — Part 1 : Kinds and quality classification

Introduction

This Japanese Industrial Standard has been prepared based on the second edition of **IEC 61190-1-2** published in 2007 with some modifications of the technical contents in order to reflect the current situation in Japan.

The portions given sidelines or dotted underlines are the matters in which the contents of the corresponding International Standard have been modified. A list of modifications with the explanations is given in Annex JA.

1 Scope

This Standard specifies the kinds and quality classification of solder paste to be used in the wiring connection of electrical equipment, electronic equipment, communication equipment or the like, and in manufacturing the parts thereof.

NOTE : The International Standard corresponding to this Standard and the symbol of degree of correspondence are as follows.

IEC 61190-1-2 : 2007 *Attachment materials for electronic assembly — Part 1-2 : Requirements for soldering pastes for high-quality interconnects in electronics assembly* (MOD)

In addition, symbols which denote the degree of correspondence in the contents between the relevant International Standard and **JIS** are IDT (identical), MOD (modified), and NEQ (not equivalent) according to **ISO/IEC Guide 21-1**.

2 Normative references

The following standards contain provisions which, through reference in this text, constitute provisions of this Standard. The most recent editions of the standards (including amendments) indicated below shall be applied.

JIS Z 3001 (series) *Welding and allied processes — Vocabulary*

JIS Z 3197 *Test methods for soldering fluxes*

NOTE : Corresponding International Standards : ISO 9455-5 : 1992 *Soft soldering fluxes — Test methods — Part 5 : Copper mirror test*, ISO 9455-6 : 1995 *Soft soldering fluxes — Test methods — Part 6 : Determination and detection of halide (excluding fluoride) content*, ISO 9455-10 : 1998 *Soft soldering fluxes — Test methods — Part 10 : Flux efficacy tests, solder spread method*, ISO 9455-13 : 1996 *Soft soldering fluxes — Test methods — Part 13 : Determination of flux spattering*, ISO 9455-15 : 1996 *Soft soldering fluxes — Test methods — Part 15 : Copper corrosion test*, ISO 9455-16 : 1998 *Soft soldering fluxes — Test methods — Part 16 : Flux efficacy tests, wetting balance method*, ISO 9455-17 : 2002 *Soft soldering fluxes — Test methods — Part 17 : Surface insulation resistance comb*

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